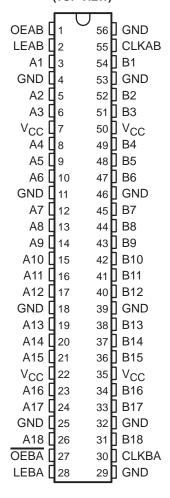
- **Members of the Texas Instruments** Widebus™ Family
- State-of-the-Art *EPIC-IIB™* BiCMOS Design Significantly Reduces Power Dissipation
- **UBT**™ (Universal Bus Transceiver) **Combines D-Type Latches and D-Type** Flip-Flops for Operation in Transparent, Latched, or Clocked Mode
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per **JEDEC Standard JESD-17**
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$
- Flow-Through Architecture Optimizes PCB Layout
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package **Using 25-mil Center-to-Center Spacings**

description

These 18-bit universal bus transceivers consist of storage elements that can operate either as D-type latches or D-type flip-flops to allow data flow in transparent or clocked modes.

Data flow in each direction is controlled by output-enable (OEAB and OEBA), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the low-to-high transition of CLKAB. When OEAB is high, the outputs are active. When OEAB is low, the outputs are in the high-impedance state.

SN54ABT16501 . . . WD PACKAGE SN74ABT16501...DGG OR DL PACKAGE (TOP VIEW)



Data flow for B to A is similar to that of A to B but uses OEBA, LEBA, and CLKBA. The output enables are complementary (OEAB is active high and OEBA is active low).

To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pulldown resistor and $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sourcing/current-sinking capability of the driver.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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SN54ABT16501, SN74ABT16501 18-BIT UNIVERSAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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description (continued)

The SN54ABT16501 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ABT16501 is characterized for operation from -40° C to 85° C.

FUNCTION TABLE[†]

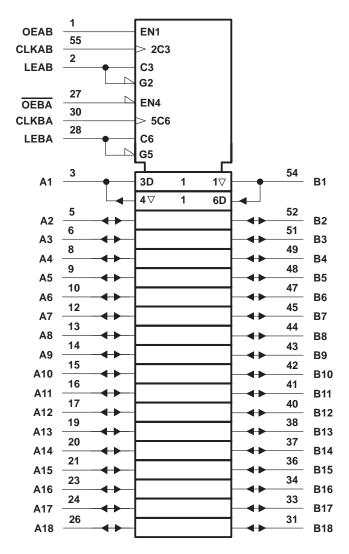
	OUTPUT			
OEAB	LEAB	CLKAB	Α	В
L	Χ	Х	Χ	Z
Н	Н	Χ	L	L
Н	Н	Χ	Н	Н
Н	L	\uparrow	L	L
Н	L	\uparrow	Н	Н
Н	L	Н	Χ	B ₀ ‡
Н	L	L	Χ	В ₀ §

[†]A-to-B data flow is shown: B-to-A flow is similar but uses OEBA, LEBA, and CLKBA.

[‡]Output level before the indicated steady-state input conditions were established, provided that CLKAB was high before LEAB went low

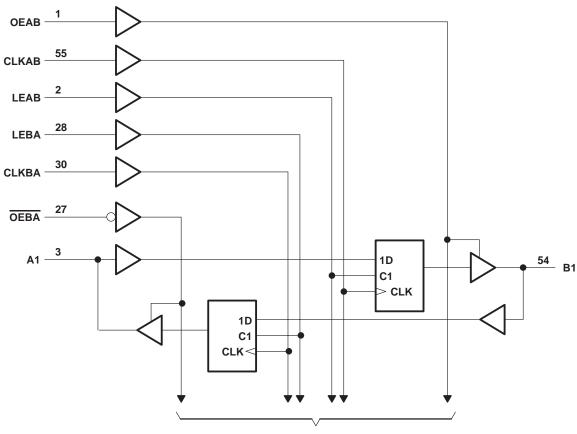
[§] Output level before the indicated steady-state input conditions were established

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



To 17 Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	\dots -0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	\dots -0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	–0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT16501	96 mA
SN74ABT16501	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DGG package	81°C/W
DL package	74°C/W
Storage temperature range, T _{stq}	. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.



recommended operating conditions (see Note 3)

			SN54ABT	16501	SN74ABT	16501	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2	EN	2		V
V _{IL}	Low-level input voltage			0.8		0.8	V
VI	Input voltage		0 0	VCC	0	VCC	V
loh	High-level output current		, , ,	-24		-32	mA
loL	Low-level output current		200	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	75	10		10	ns/V
T _A	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		Т	A = 25°C	;	SN54ABT16501		SN74ABT16501		UNIT	
PAI	RAMETER	TEST CO	NDITIONS	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNII	
VIK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5			
\ \/a		$V_{CC} = 5 V$	$I_{OH} = -3 \text{ mA}$	3			3		3		V	
VOH		V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2				V	
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2			
VOL		V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V	
VOL		VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V	
V _{hys}					100			2			mV	
١,	Control inputs	V _{CC} = 5.5 V,	V _I = V _{CC} or GND			±1		<u>⊬</u> ±1		±1	μΑ	
11	A or B ports	VCC = 5.5 V,	AL = ACC OLOUP			±100		±100		±100	μΛ	
lozh‡		$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.7 \text{ V}$			50		50		50	μΑ	
lozL [‡]		$V_{CC} = 5.5 \text{ V},$	V _O = 0.5 V			-50	S	- 50		-50	μΑ	
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100	90			±100	μΑ	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50	d'a	50		50	μА	
ΙΟ§		$V_{CC} = 5.5 \text{ V},$	V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA	
		V _{CC} = 5.5 V,	Outputs high			3		5		3		
Icc	A or B ports	$I_{O} = 0$,	Outputs low			76		76		76	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled			3.3		5.3		3.3		
	Control inputs	V _{CC} = 5.5 V, One	nput at 3.4 V,			5		6		5	mA	
∆ICC¶	A or B ports	Other inputs at V _{CC} or GND				1.5		1.5		1.5	IIIA	
Ci	Control inputs	V _I = 2.5 V or 0.5 V			4						pF	
C _{io}	A or B ports	$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$	/		8						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				SN54AB1	Г16501	SN74AB1	16501	UNIT	
				MIN	MAX	MIN	MAX	UNIT	
fclock	Clock frequency, CLKAB or	0	105	0	105	MHz			
. #	Pulse duration LEAB or LEBA high		3.3	EN	3.3		ns		
ι _Μ "	t _W # Pulse duration CLKAB or CLKBA high or low			4.7		4.7		119	
		A before CLKAB↑ or B before CLKBA1	4 4	2	3.5				
t _{su}	Setup time	A before LEAB↓ or B before LEBA↓	CLK high	4		4		ns	
		CLK low		1.5		1.5			
th Hold time		A after CLKAB↑ or B after CLKBA↑	& 1		1		ns		
^t h	HOIG UITIE	A after LEAB↓ or B after LEBA↓	2.5		2.5		113		

[#]This parameter is specified by design, but not production tested.



[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡]The parameters IOZH and IOZL include the input leakage current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[¶] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

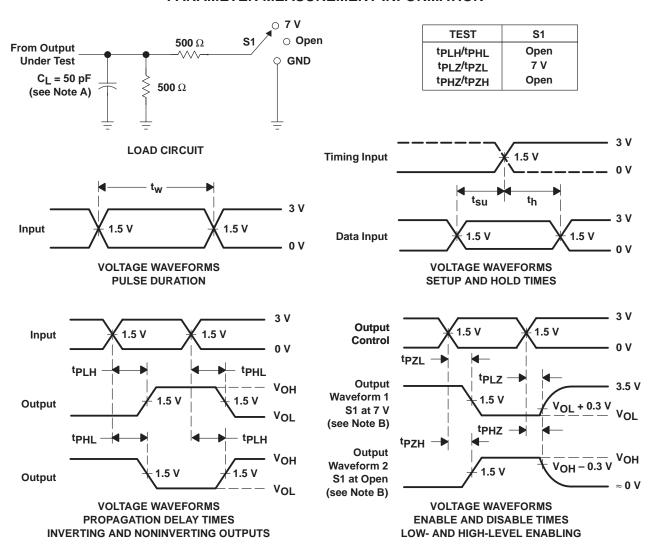
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C		V, C SN54		Г16501	SN74AB1	Г16501	UNIT
	(IIVI OT)	(0011 01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}	CLKAB or CLKBA		105	160		105		105		MHz
^t PLH	A or B	B or A	1	2.6	3.4	1	3.9	1	3.7	20
^t PHL	AUID	BULA	1	2.6	3.4	1	4.1	1	4	ns
^t PLH	LEAB or LEBA	B or A	1.3	3.3	4.3	1.3	5.4	1.3	5.1	ns
^t PHL	LEAD OF LEDA	BULA	1.4	3.1	4.1	1.4	4.6	1.4	4.4	115
^t PLH	CLKAB or CLKBA	B or A	1.5	3.5	4.5	1.5	5.3	1.5	5	ns
^t PHL	CLNAD OF CLNBA	BUIA	1.3	3.1	4.1	1.3	4.6	1.3	4.4	115
^t PZH	0540 0504	D.o. A	1	3	4	& 1	4.8	1	4.7	
t _{PZL}	OEAB or OEBA	B or A	2.6	4.9	5.9	2.6	6.6	2.6	6.5	ns
^t PHZ	OEAB or OEBA	B or A	1.6	3.9	4.9	1.6	5.9	1.6	5.8	no
t _{PLZ}	OEAD OF OEBA	DULA	1.1	3.4	4.4	1.1	5.1	1.1	4.9	ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{Q} = 50 Ω , t_{f} \leq 2.5 ns, t_{f} \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







i.com 5-Sep-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ABT16501DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16501DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16501DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16501DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16501DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16501DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

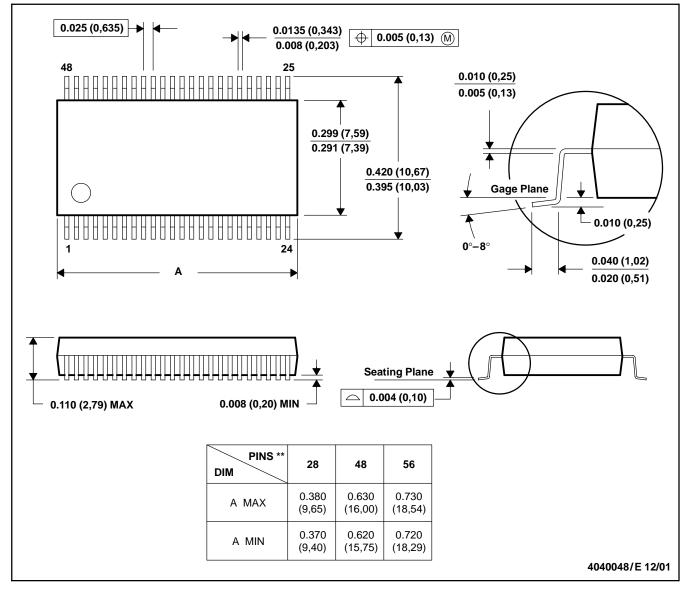
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DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

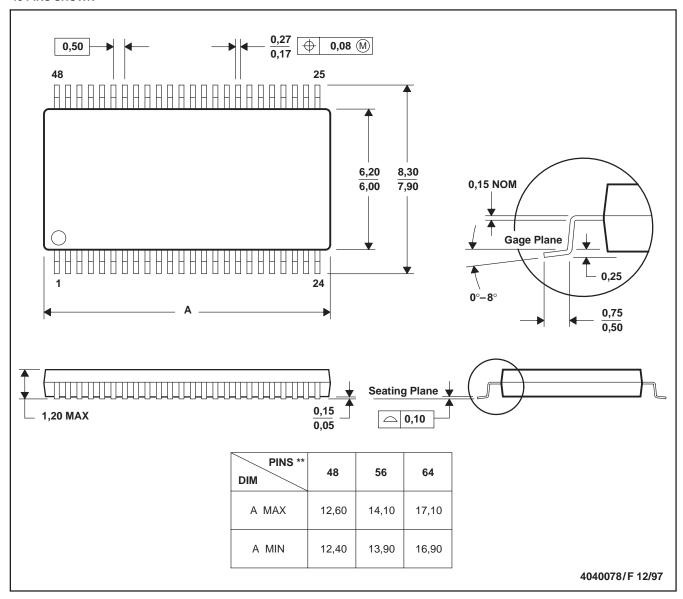
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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